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Renesas Technology Corp.
Customer Support Dept.
April 1, 2003

Cautions

Keep safety first in your circuit designs!

1. Renesas Technology Corporation puts the maximum effort into making semiconductor products better and more reliable, but there is always the possibility that trouble may occur with them. Trouble with semiconductors may lead to personal injury, fire or property damage.

Remember to give due consideration to safety when making your circuit designs, with appropriate measures such as (i) placement of substitutive, auxiliary circuits, (ii) use of nonflammable material or (iii) prevention against any malfunction or mishap.

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HSM276S

Silicon Schottky Barrier Diode for Balanced Mixer

RENESAS

ADE-208-039F (Z)

Rev.6
Apr. 2002

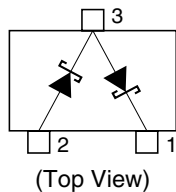
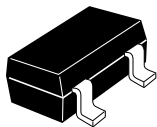
Features

- High forward current, Low capacitance.
- HSM276S which is interconnected in series configuration is designed for balanced mixer use.
- MPAK package is suitable for high density surface mounting and high speed assembly.

Ordering Information

Type No.	Laser Mark	Package Code
HSM276S	C2	MPAK

Pin Arrangement



1. Cathode 2
2. Anode 1
3. Cathode 1
Anode 2

Absolute Maximum Ratings

(Ta = 25°C)

Item	Symbol	Value	Unit
Reverse voltage	V_R	3	V
Average rectified current	I_o *1	30	mA
Junction temperature	Tj	125	°C
Storage temperature	Tstg	-55 to +125	°C

Note: 1. Per one device

Electrical Characteristics *1

(Ta = 25°C)

Item	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse voltage	V_R	3.0	—	—	V	$I_R = 1$ mA
Reverse current	I_R	—	—	50	μA	$V_R = 0.5$ V
Forward current	I_F	35	—	—	mA	$V_F = 0.5$ V
Capacitance	C	—	—	0.90	pF	$V_R = 0.5$ V, f = 1 MHz
Capacitance deviation	ΔC	—	—	0.10	pF	$V_R = 0.5$ V, f = 1 MHz
ESD-Capability *2	—	30	—	—	V	C = 200 pF, R = 0 Ω , Both forward and reverse direction 1 Pulse.

Notes: 1. Per one device

2. Failure criterion ; $I_R \geq 100$ μA at $V_R = 0.5$ V

Main Characteristic

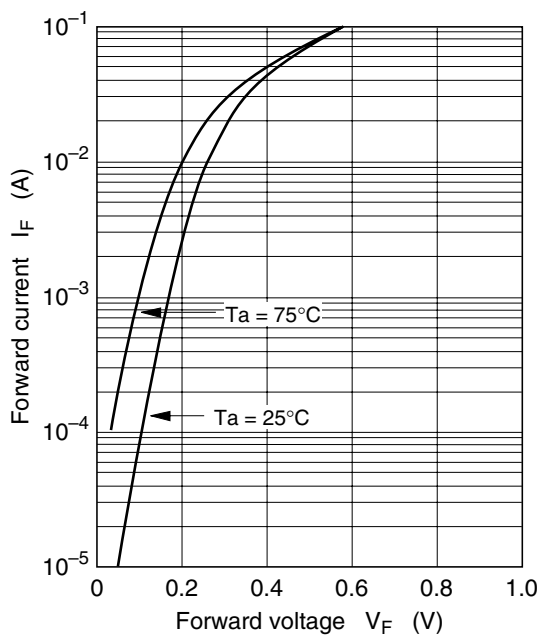


Fig.1 Forward current vs. Forward voltage

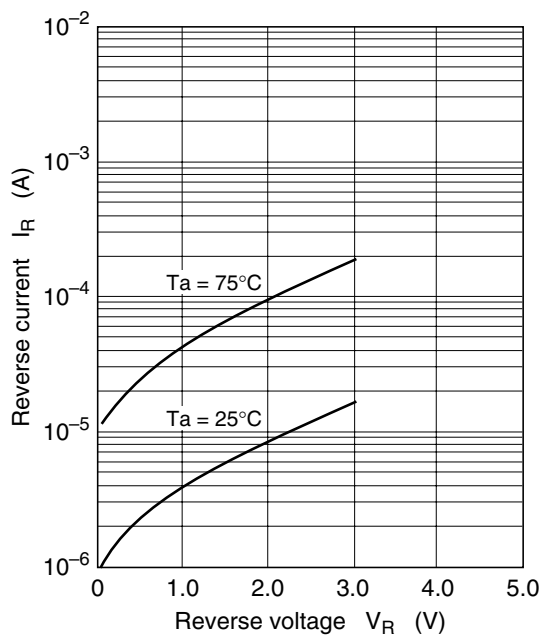


Fig.2 Reverse current vs. Reverse voltage

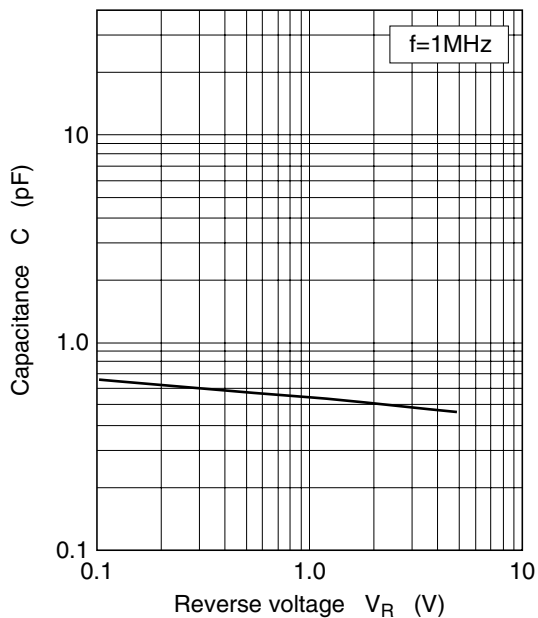
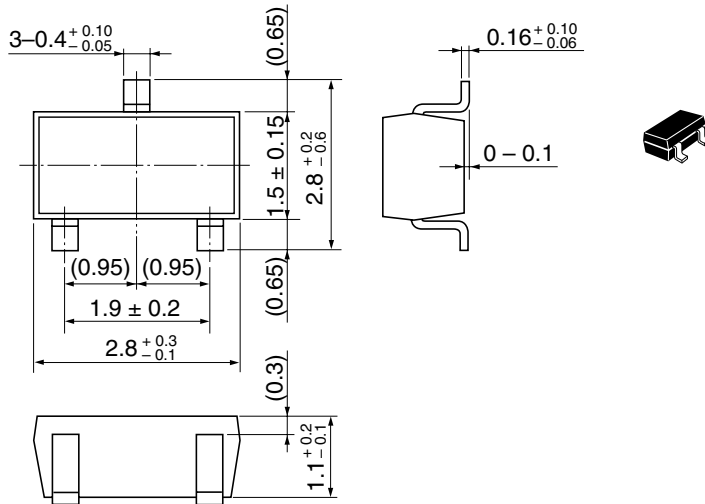


Fig.3 Capacitance vs. Reverse voltage

Package Dimensions

As of January, 2002

Unit: mm



Hitachi Code	MPAK
JEDEC	—
JEITA	Conforms
Mass (reference value)	0.011 g

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